

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING SENT VIA FACSIMILE TO: COMMI
FOR PATENTS, WASHINGTON, D.C. 20231, ON APRIL 17, 2002
Depositor: ROSE MILLER

Rose Miller 4/17/02
Signature And Date

#8/Response
4/18/02
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

April 17, 2002

Vincent J. McGahay, et al.

Examiner: Deven M. Collins

Serial No. 09/849,530

Group Art Unit: 2823

Filing Date May 7, 2001

Title: Method For Improving
Adhesion To Copper

IBM Corporation - IPLaw Dept.
Dept. 18G/Bldg. 300-482
2070 Route 52
Hopewell Junction, NY 12533

AMENDMENT

Commissioner of Patents
and Trademarks
Washington, D.C. 20231

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APR 17 2002

TECHNOLOGY CENTER 2800

Sir:

Responsive to the Office Action dated 02/14/02, Applicant respectfully request
the Examiner to consider the following Remarks.